

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
600V	$0.35\Omega @ 10V$	24A

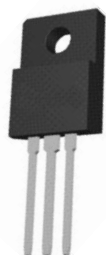
Feature

- Self-aligned planar Technology
- Low conduction loss

Application

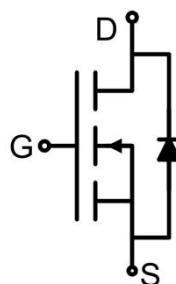
- Uninterruptible power supply (UPS)
- Power factor correction (PFC)

Package

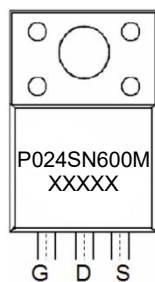


ITO-220AB

Circuit diagram



Marking



Absolute maximum ratings ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS}=0V$)	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current	I_D	24	A
Pulsed Drain Current ¹⁾	I_{DM}	100	A
Power Dissipation ²⁾	P_D	189	W
Single Pulse Avalanche Energy ³⁾	E_{AS}	2880	mJ
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.66	$^{\circ}\text{C/W}$
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-55 ~ +150	$^{\circ}\text{C}$

Electrical characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	600			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =600V, V _{GS} =0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} =10V, I _D =12.5A		0.26	0.35	Ω
Dynamic characteristics ⁴⁾						
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f =1MHz		4008		pF
Output Capacitance	C _{oss}			423		
Reverse Transfer Capacitance	C _{rss}			62		
Total Gate Charge	Q _g	V _{DS} =480V, V _{GS} =10V, I _D =24A		122		nC
Gate-Source Charge	Q _{gs}			18		
Gate-Drain Charge	Q _{gd}			61		
Turn-on delay time	t _{d(on)}	V _{DD} =300V, I _D =24A, R _G =25Ω		67		nS
Turn-on rise time	t _r			53		
Turn-off delay time	t _{d(off)}			522		
Turn-off fall time	t _f			94		
Source-Drain Diode characteristics						
Diode Forward Current	I _S	T _C =25℃			24	A
Diode Forward voltage	V _{SD}	V _{GS} =0V, I _{SD} =12.5A			1.4	V
Reverse Recovery Time	T _{rr}	V _{GS} =0V, I _S =24A di _F /dt = 100A/μs		800		nS
Reverse Recovery Charge	Q _{rr}			8.46		μC

Notes:

- 1) The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2) The power dissipation is limited by 150 $^{\circ}\text{C}$ junction temperature.
- 3) The EAS data shows Max. rating .L=4.1mH, $I_{AS}=24A$, $V_{DD}=50V$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$.
- 4) Guaranteed by design, not subject to production testing.

Typical Characteristics

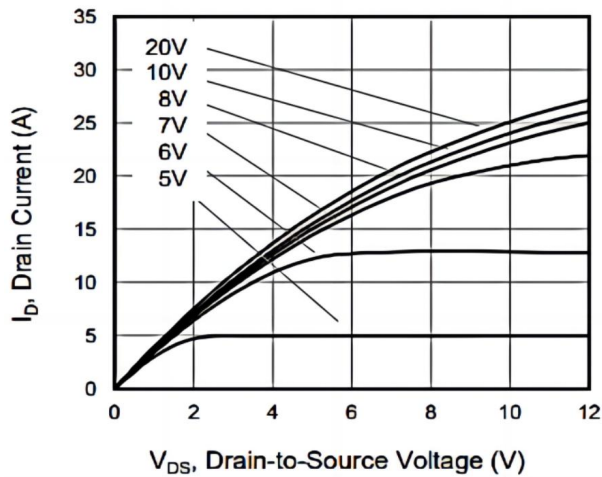


Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

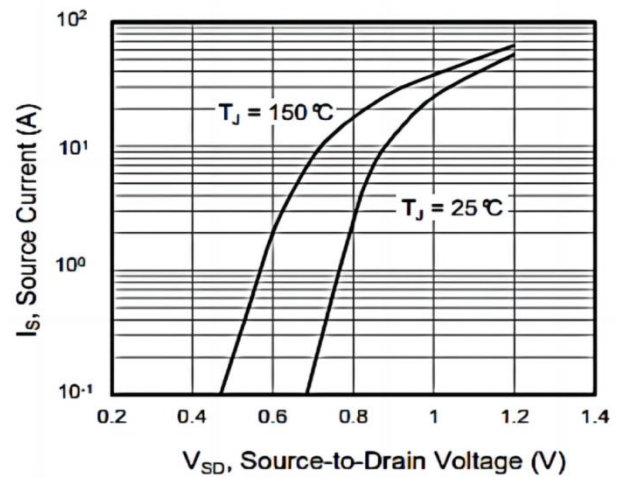


Figure 2. Body Diode Forward Voltage

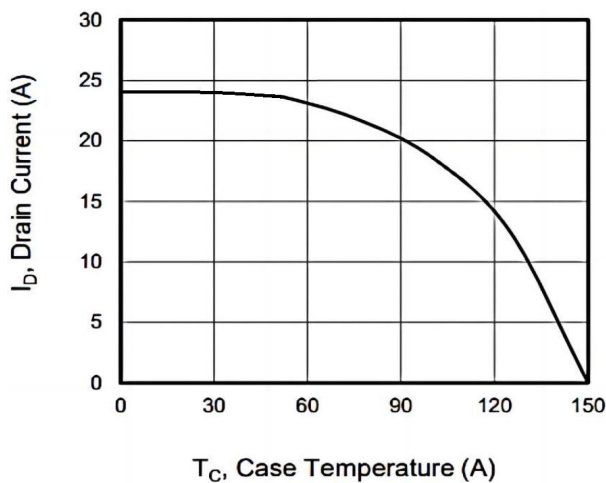


Figure 3. Drain Current vs. Temperature

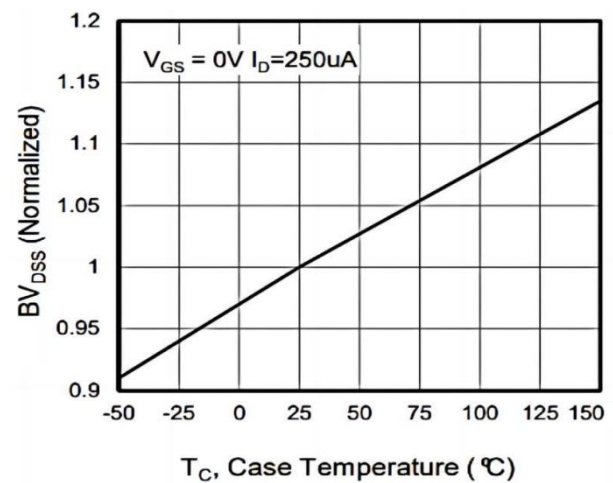


Figure 4. BVDSS Variation vs. Temperature

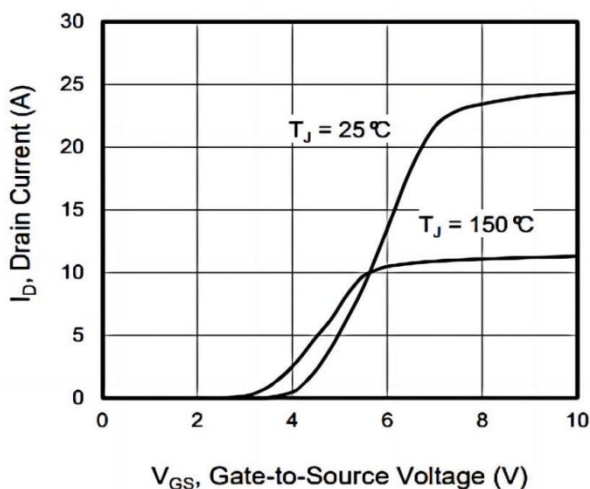


Figure 5. Transfer Characteristics

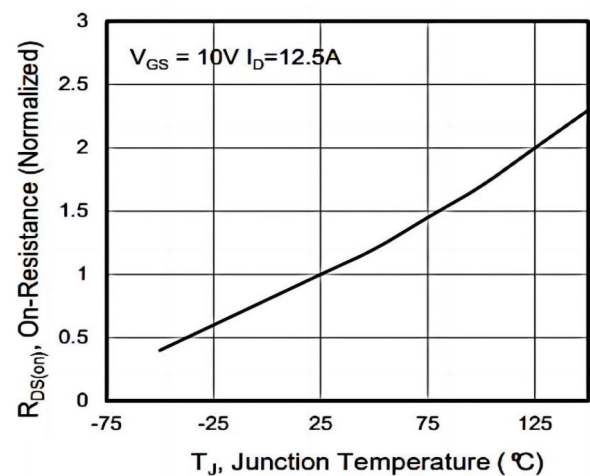


Figure 6. On-Resistance vs. Temperature

Typical Characteristics

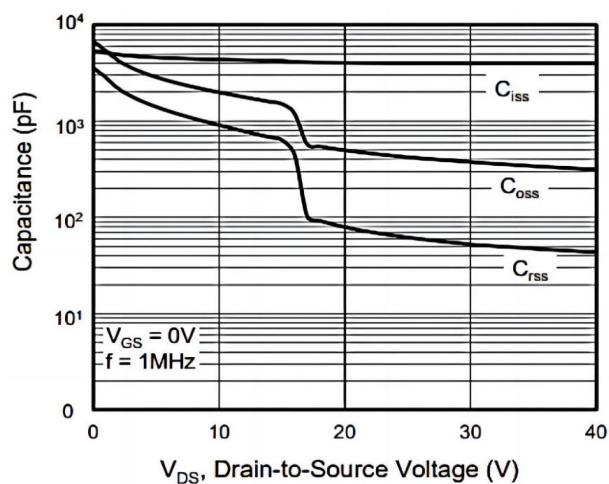


Figure 7. Capacitance

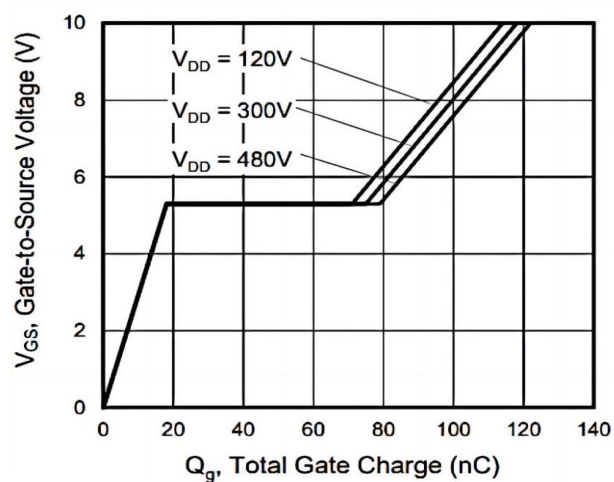


Figure 8. Gate Charge

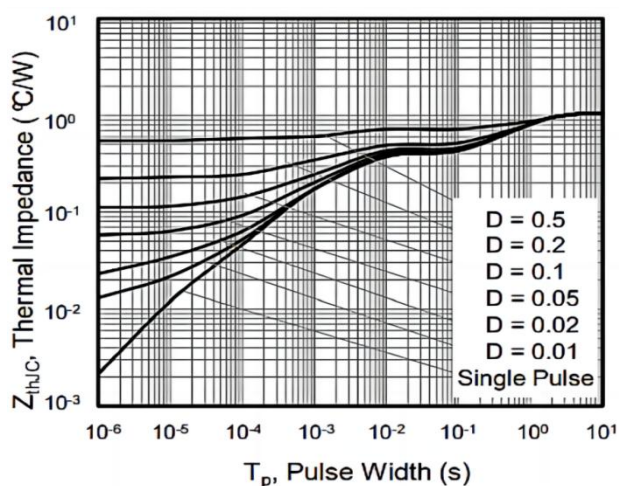
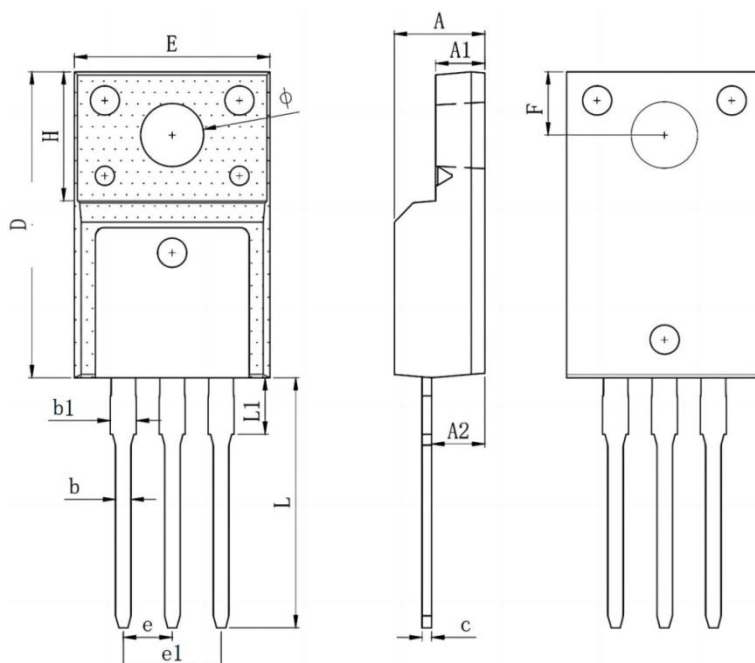


Figure 9. Transient Thermal Impedance

ITO-220AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.500	5.000	0.177	0.197
A1	2.340	2.840	0.092	0.112
A2	2.400	3.400	0.094	0.134
b	0.700	0.950	0.028	0.037
b1	1.050	1.550	0.041	0.061
c	0.400	0.650	0.016	0.026
D	15.570	16.170	0.613	0.637
H	6.700 REF.		0.264 REF.	
E	9.860	10.460	0.388	0.412
e	2.540 BSC.		0.100 BSC.	
e1	5.080 BSC.		0.200 BSC.	
L	12.650	13.300	0.498	0.524
L1	2.780	3.380	0.109	0.133
F	3.150	3.550	0.124	0.140
φ	3.000	3.650	0.118	0.144